

Claims

- [c1] 1. Integrated electronic container, made of a rack structure (1) for electrical and electronic equipment, comprising a heat sink (2) and connection elements (3), characterized because said heat sink (2) as well as the connection elements (3) are integrated becoming part of the previously mentioned rack structure (1), distributed at opposite extremes, being placed the electronic circuits in the interior of the rack structure (1), in printed board boards, with a thermal gel that transmits the heat generated by the electronic components to the heat sink (2).
- [c2] 2.– Integrated electronic container, according to claim 1, characterized because the mentioned rack structure (1) is airtight, consisting of at least two bodies, a receiving body in which base the connectors are located (3) and a cover where the heat sink is placed (2), being the closure between both bodies of the rack provided with airtight joints.
- [c3] 3. Integrated electronic container, according to claim 1, characterized in that said rack structure (1) consists of more than two bodies, all of them being provided with airtight joints.

[c4] 4. Integrated electronic container, according to claim 1, characterized in that said rack structure (1) consists of more than two bodies, all of them being provided with airtight joints.

[c5]